

IBM z15 Highlights

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Agenda

- **z15 T02 (/T01)**
- **Compression**
- **HMC / SE**

IBM z15 T02 und T01



IBM z15
Model T02



IBM z15
Model T01

IBM z15 Model T02 Announcement – 14. April 2020
(General Availability 15. May 2020)

IBM Z – Naming for IBM z15™ Model T01 and T02

Brand Name:	IBM
Product Class:	IBM mainframe
Family Name:	IBM Z®
Family Short Name:	Z
Product Line Name:	IBM Z®
Product Line Short Name:	Z
Product Name:	IBM z15™
Short Name:	z15™
Model and Processor Capacity Features:	T01, Features: Max34, Max71, Max108, Max145, Max190 T02, Features: Max4, Max13, Max21, Max31, Max65
Machine Type:	T01 -> 8561 T02 -> 8562

IBM Z and LinuxONE

IBM Z

Can run all workload



LinuxONE

Specialized for Linux on Z workload

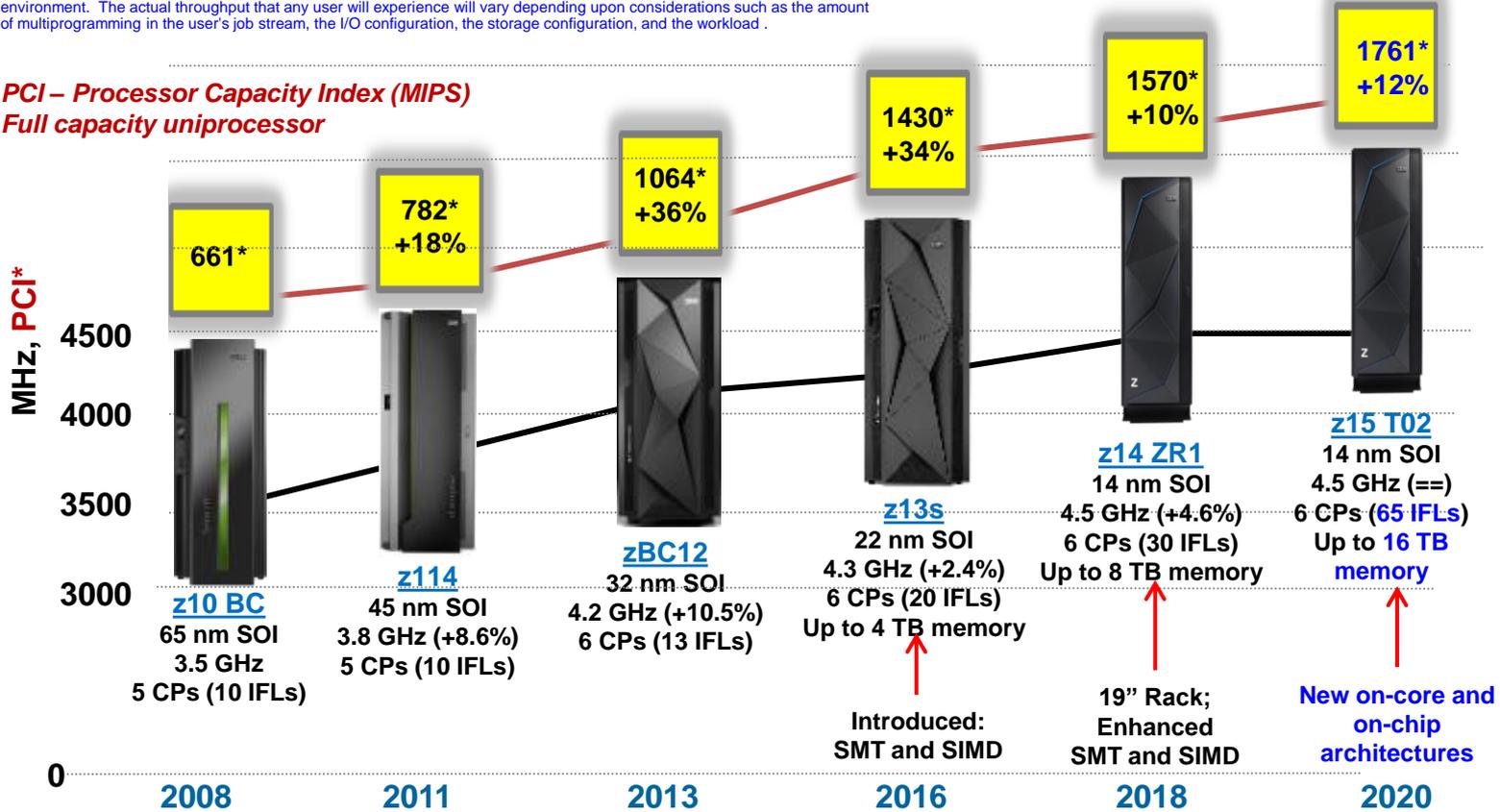
LinuxONE III LT1 / LT2

*In Switzerland, Phoenix Systems AG
has now a LinuxONE III*

z15 T02 Continues the CMOS Mainframe Heritage

*Capacity and performance ratios are based on measurements and projections using standard IBM benchmarks in a controlled environment. The actual throughput that any user will experience will vary depending upon considerations such as the amount of multiprogramming in the user's job stream, the I/O configuration, the storage configuration, and the workload .

PCI – Processor Capacity Index (MIPS)
Full capacity uniprocessor



*NOTE: PCI (MIPS) Tables are NOT adequate for making comparisons of IBM Z processors in proposals

4./5. May 2021

8562-T02 Processing Units

Model	Feature	Drawers/ Cores	PU SCM/ CPs	IFLs/ uIFLs	zIIPs	ICFs	Std SAPs	Optional SAPs	Std. Spares	IFP
T02	Max4	1/8	1 0-4	0-4 0-3	0-2	0-4	2	0-2	1	1
	Max13	1/17	2 0-6	0-13 0-12	0-7	0-13	2	0-2	1	1
	Max21	1/27	3 0-6	0-21 0-20	0-12	0-21	3	0-2	2	1
	Max31	1/38	4 0-6	0-31 0-30	0-12	0-31	4	0-8	2	1
	Max65	2/76	8 0-6	0-65 0-64	0-12	0-65	8	0-8	2	1

1. At least one CP, IFL, or ICF must be purchased in every machine.
2. Two zIIPs may be purchased for each CP purchased if cores are available. (2:1). This remains true for sub-capacity CPs and for “banked” CPs.
3. “uIFL” = Unassigned IFL
4. The IFP is conceptually an additional, special purpose SAP – used by PCIe I/O features (e.g. RoCE, CE LR), and some other functions.

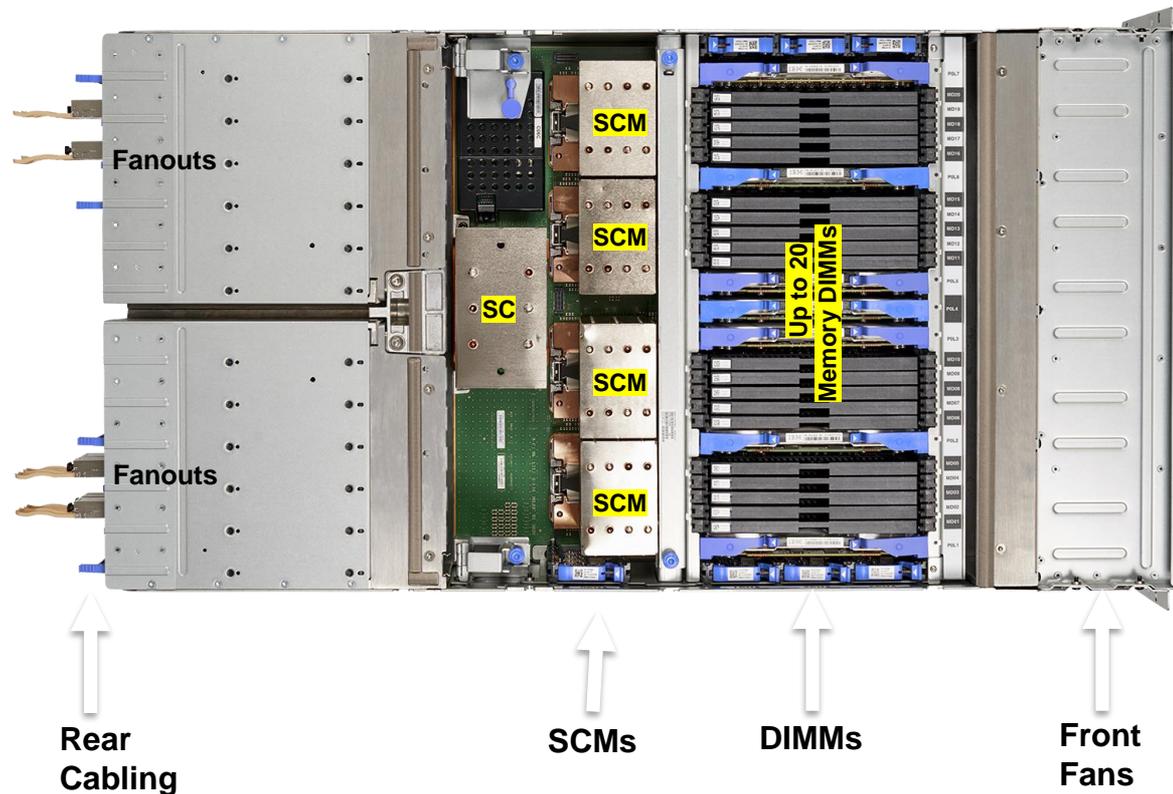
CPC drawer

Each PU Single Chip Module (SCM):

- 14nm
- 7 to 11 cores
- One Memory controller
- Five DDR4 DIMM

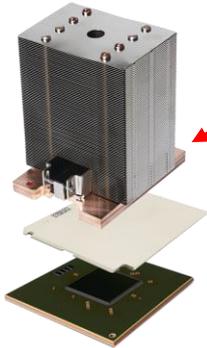
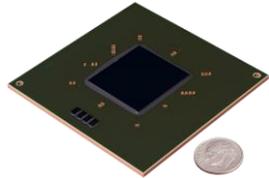
Each CPC drawer:

- 12 PCIe+ fanout slots for PCIe+ I/O drawer fanout or ICA SR coupling link.
- Single System Controller (SC) 960MB L4

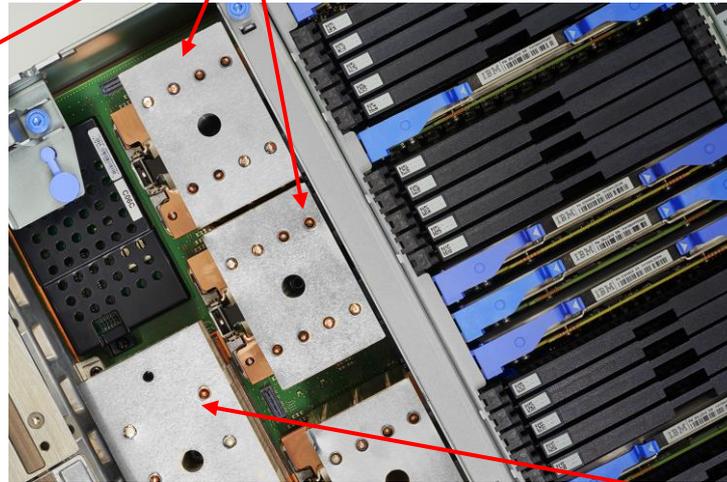


z15 Model T02 PU and SC SCM assemblies

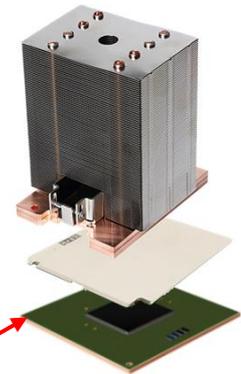
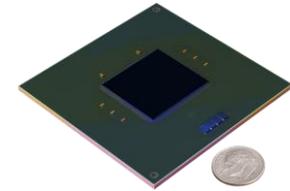
PU SCM



PU SCM (air cooled) with heatsink

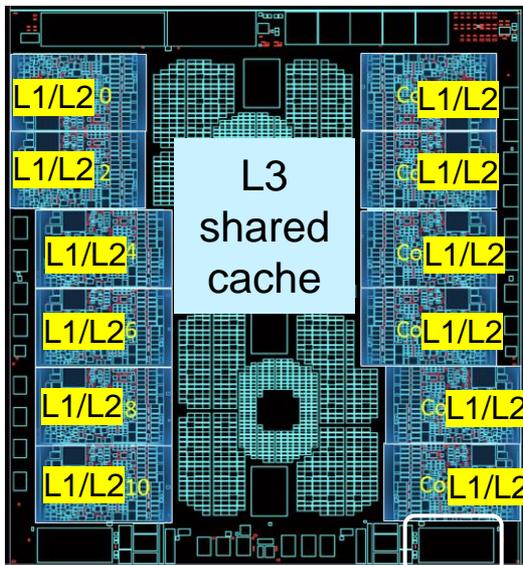


SC SCM



1x SC SCM (air cooled) with heatsink

12-Core / PU SCM detail



- On Core L1/L2 Cache
 - Protocol changes to reduce latency
- On chip L3 Cache
 - Protocol changes to reduce latency
 - Communicates with cores, memory, I/O and system controller single chip module.

- 14nm technology
 - 17 layers of metal
 - 9.2B transistors versus 6.2B on z14

- 20% reduction area
- 20% reduction in power
- 4.5 GHz
- Reduced cycles per instruction

Cache Summary - Comparison to z14 ZR1

Grow L2 (instruction) increase by 2x.	2MB[i] 4MB[d] to 4MB[i] 4MB[d]
Grow L3 increase by 2x.	128MB to 256MB
Grow L4 by 43%	672MB to 960MB*

*For a Max65 system (two CPC drawer), the L4 cache is 1920 MB

Memory Considerations

Model	Feature	Min	Max
T02/LT2	Max4	64 GB	2 TB
T02/LT2	Max13	64 GB	4 TB
T02/LT2	Max21	64 GB	4 TB
T02/LT2	Max31	64 GB	8 TB
T02/LT2	Max65	64 GB	16 TB

Concurrent memory upgrades via licensed internal code (LICC) are available at several capacity levels.

- DDR4 Memory DIMMS (32, 64, 128, 256, 512 GB)
- An additional **160 GB** of memory is reserved above the customer purchase amount for the Hardware System Area (HSA).
- An additional **20%** of memory is reserved above the customer purchase amount for Redundant Array of Independent Memory (RAIM).

z15 8561 vs. 8562



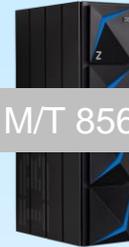
- Announced – 09/12/2019, GA – 09/23/2019
- **M/T 8561 - Model T01**
- **Five features – Max34, Max71, Max108, Max145, Max190**
 - Up to 190 customer configurable engines
- Sub-capacity Offerings for **up to 34 CPs**
- **PU (Engine) Characterization**
 - CP, IFL, ICF, zIIP, SAP, IFP (No zAAPs)
- **On Demand Capabilities**
 - CoD: CIU, CBU, On/Off CoD, CPE
 - System Recovery Boost Upgrade
- **Memory – up to 40 TB**
 - Up to 16 TB per LPAR (OS dependent)
 - **256 GB Fixed HSA**
 - Virtual Flash Memory (zFlash Express replacement (0.5 TB/feature, up to 12 features))
- **8561 Channels**
 - **Dual PCIe+ Gen3 16 GBps channel buses**
 - Six LCSSs, up to 85 LPARs
 - Four Subchannel Sets per LCSS
 - **OSA-Express7S** (NB, 25GbE NB or CF)
 - OSA-Express6S and 5S (CF)
 - **FICON Express16SA** (NB)
 - FICON Express16S+, 16S and 8S (CF)

Common Channels

- IBM zHyperLink Express1.1 (NB)
- IBM zHyperLink Express (CF)
- **10 and 25 GbE RoCE Express2.1** (NB)
- 10 and 25GbE RoCE Express2 (CF)
- HiperSockets™ – up to 32
- 10 GbE RoCE Express (CF)
- Shared Memory Communications - Direct Memory Access (SMC-D)
- **Crypto Express7S** (6S and 5S CF)
- Parallel Sysplex clustering:
 - **Coupling Facility Control Code Level 24**
 - Support for 384 Coupling CHPIDs per CPC
 - Support for 64 Internal Coupling Links
 - **CF Resiliency enhancements**
 - **ICA SR1.1 (PCIe) Coupling (NB)**
 - ICA SR (PCIe) Coupling (CF)
 - Coupling Express Long Reach (NB or CF)

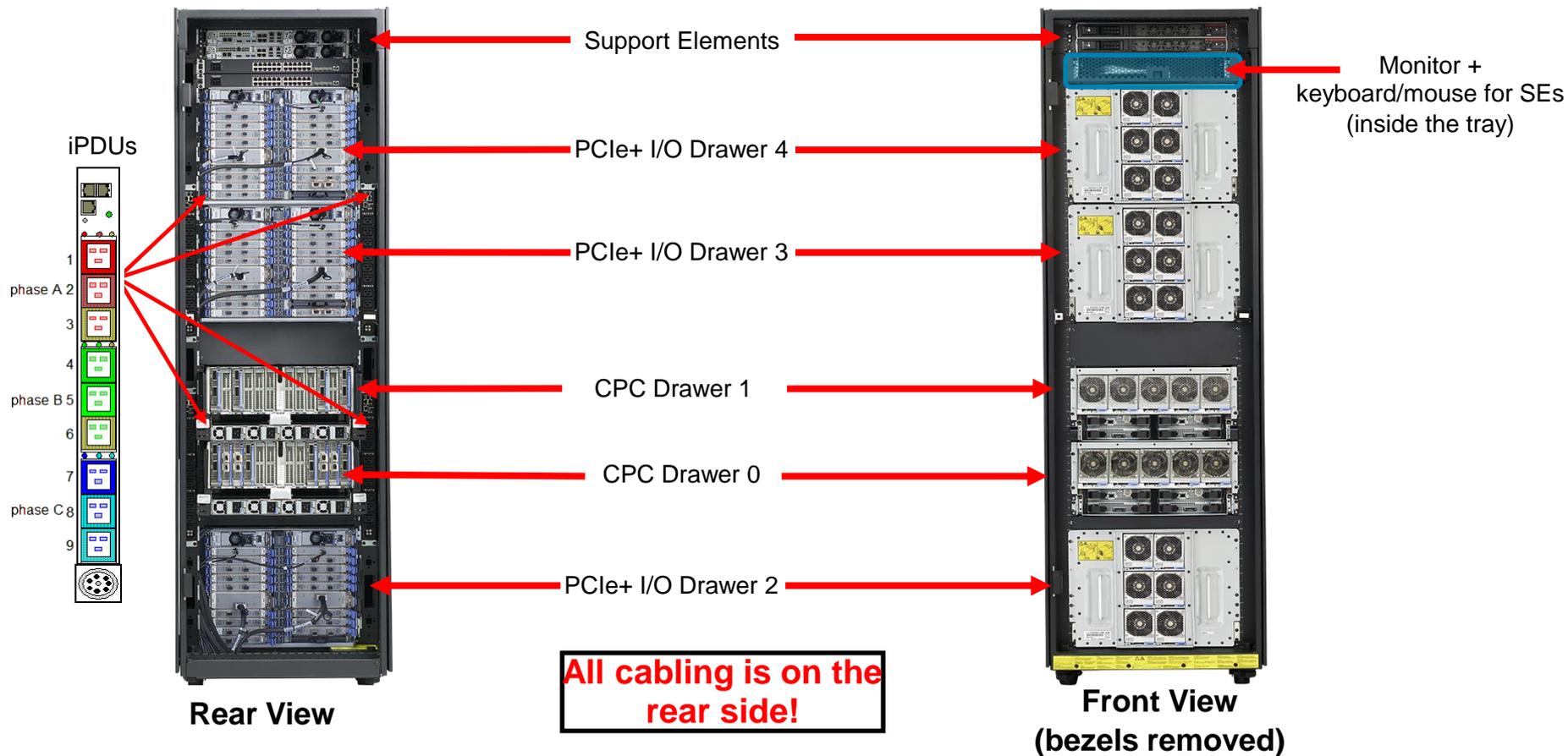
- Operating Systems
 - z/OS®, z/VM®, z/VSE, z/TPF, Linux on IBM Z, KVM for IBM Z
 - **System Recovery Boost**
 - Dynamic I/O for Standalone CF CPCs
- IBM Dynamic Partition Manager (DPM)
- IBM Secure Service Container
- **IBM Integrated Accelerator for zEDC (On-chip compression Accelerator – zEDC Express replacement)**
- **IBM Z Hardware Management Appliance**
- **Secure Execution for Linux**
- **IBM Fibre Channel Endpoint Security (8561 only)**
- Precision Time Protocol

in blue: new



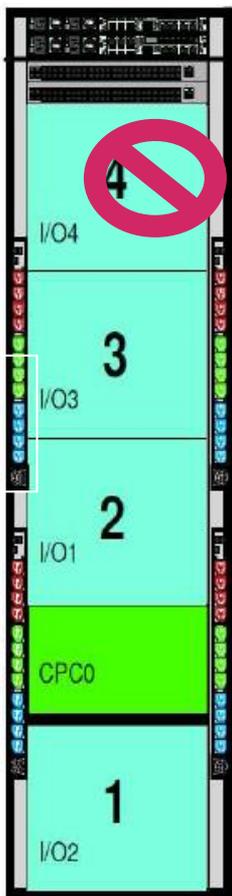
- Announced – 04/14/2020, GA – 05/15/2020
- **M/T 8562 - Model T02**
- **Five features – Max4, Max13, Max21, Max31, Max65**
 - Up to 65 customer configurable engines (max. 6 CPs)
- Sub-capacity Offerings for up to 6 CPs
- **PU (Engine) Characterization**
 - CP, IFL, ICF, zIIP, SAP, IFP (No zAAPs)
- **On Demand Capabilities**
 - CoD: CIU, CBU, On/Off CoD, CPE
- **Memory – up to 16 TB**
 - Up to 8 TB per LPAR (OS dependent)
 - **160 GB Fixed HSA**
 - Virtual Flash Memory (zFlash Express replacement (0.5 TB/feature, up to 4 features))
- **8562 Channels**
 - **Dual PCIe+ Gen3 16 GBps channel buses**
 - Three LCSSs, up to 40 LPARs
 - Three Subchannel Sets per LCSS
 - **OSA-Express7S 25 GbE** (NB and CF)
 - **OSA-Express 6S** (NB and CF)
 - OSA-Express5S (CF)
 - **FICON Express16S+** (NB or CF),
 - FICON Express16S and 8S (CF)

z15 Model T02 Max65

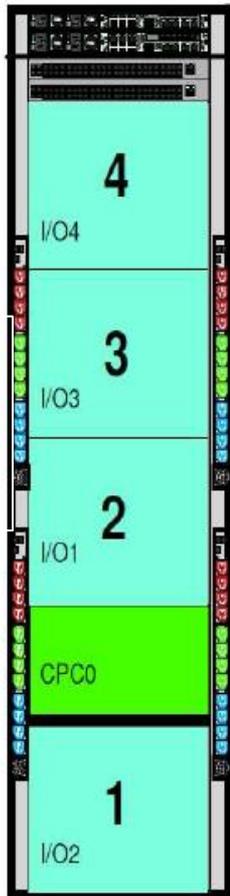


z15 T02 / LT2 I/O and CPC drawer config options

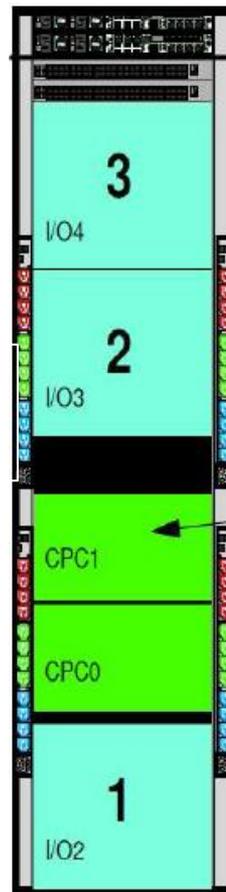
Max4
Up to
48 slots



Max13
Max21
Max31
Up to 64
slots



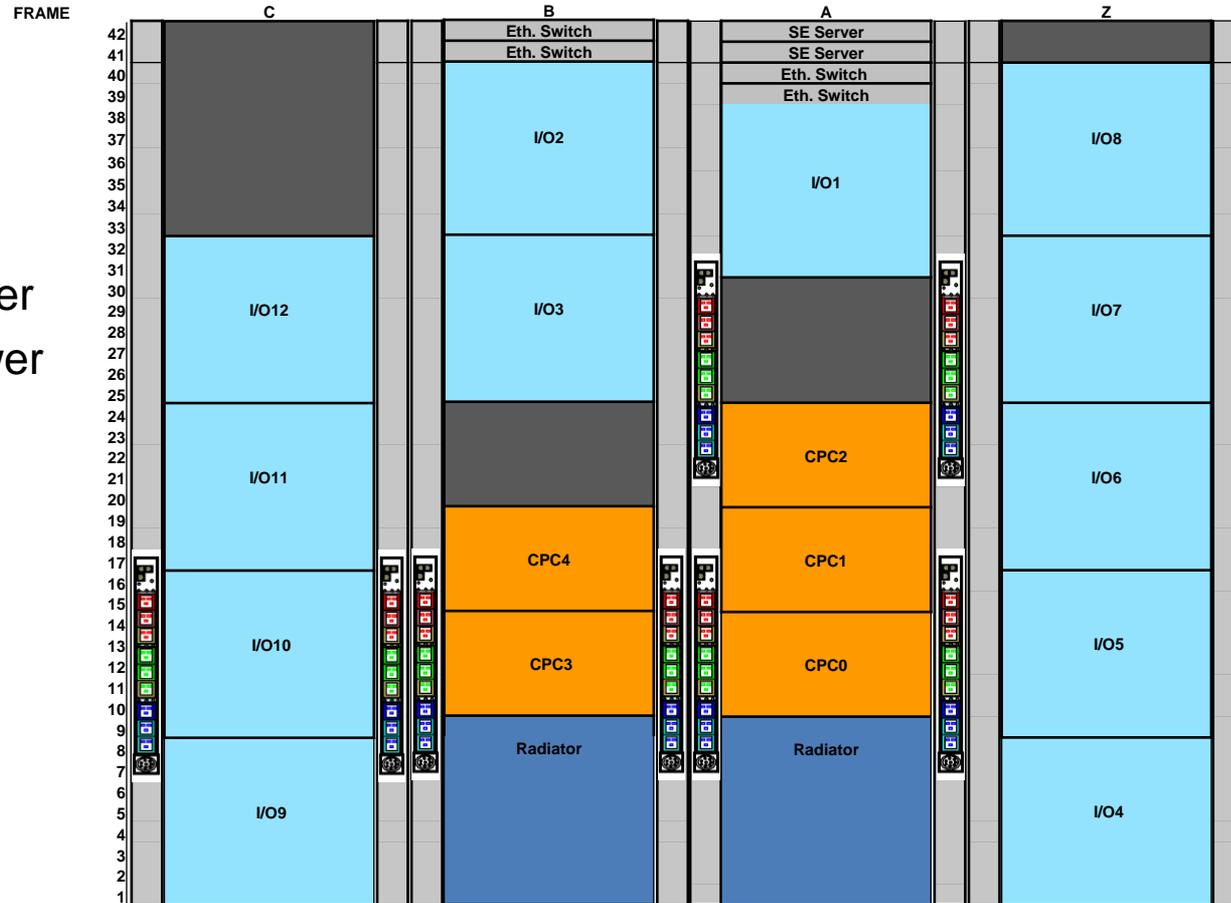
Max65
Up to
48 slots



Bold numbers
indicate installation
order.

z15 T01 front view (PDU, Four Frames, Z, A, B, C – Max190)

- Max 12 I/O drawer
- Max 5 CPC drawer



DS8910F into z15 Model T02 / LT2



IBM z15 Model
T02

~ 500 TB
capacity



IBM DS8910F
Delivering an end-to-end solution into a single 19-
inch standard rack



IBM LinuxONE III
Model LT2

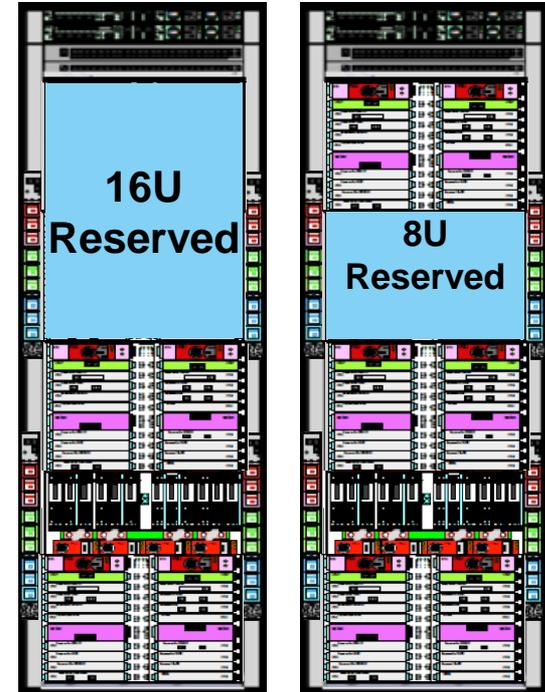
IBM z15 T02 / LT2 – 16U / 8U Reserved Space

T02 or LT2

- 16U Reserved Space
 - DS8910F Model 993

LT2

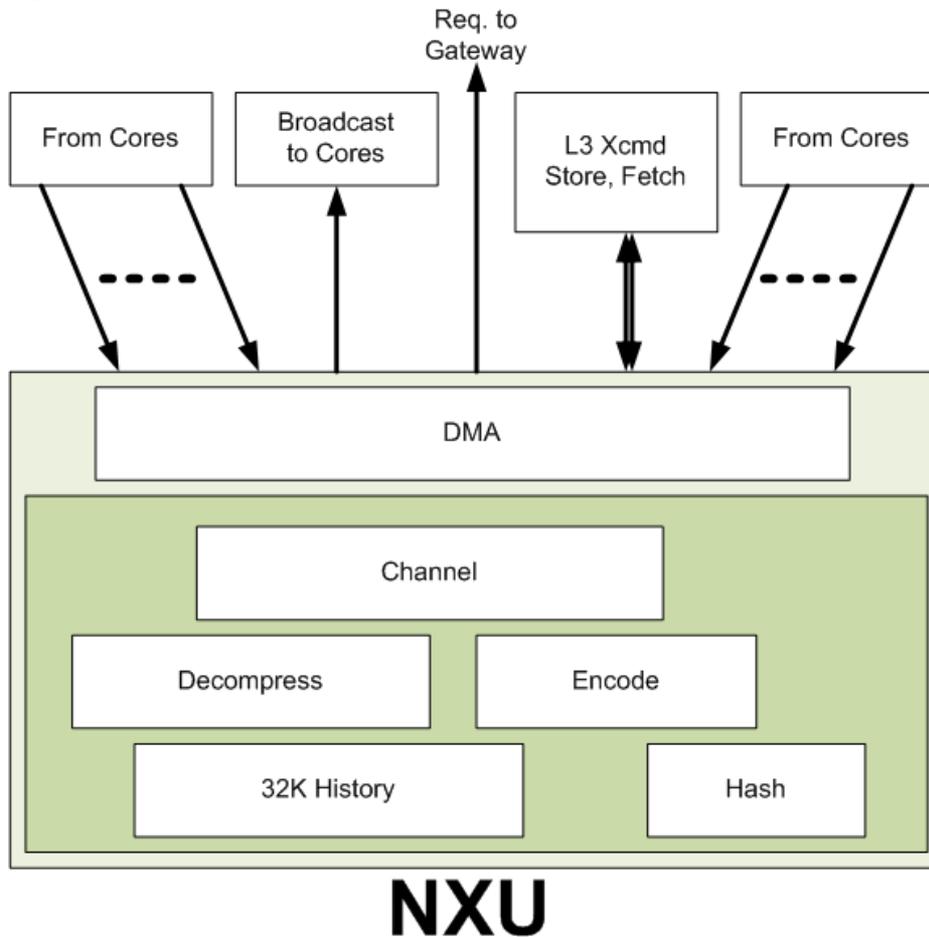
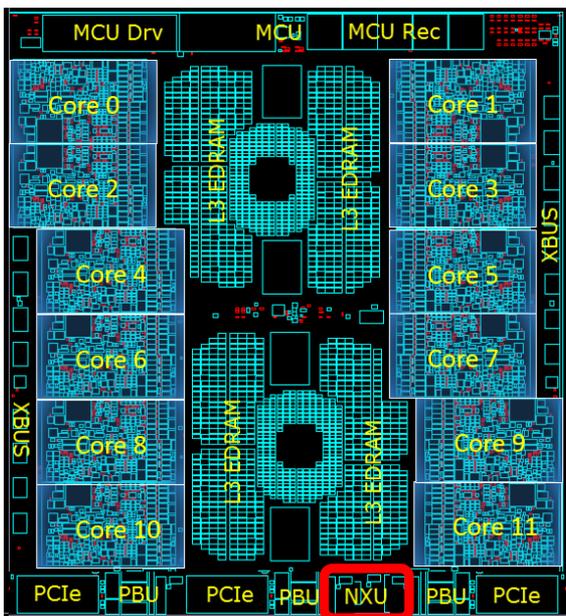
- 8U Reserved Space
 - One or Two FS9200 + One or Two 8977-T32 switches
or
 - One or Two FS7200 + One or Two 8977-T32 switches
- Both needs single phase power



IBM Integrated Accelerator for zEnterprise Data Compression (zEDC)

z15 chip design incorporates a new compression unit
(one per PU SCM) for handling DEFLATE/gzip/zlib operations
This is the zEDC Express PCIe feature replacement

z15 Integrated Accelerator – Design Overview



z/OS Software Feature Exploitation zEnterprise Data Compression

z14

z15

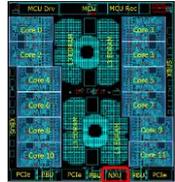


**Chargeable:
zEDC Hardware
I/O feature
required.**

**z/OS software feature
required for exploitation
of:**

- z/OS SMF Logstream
- z/OS QSAM/BSAM
- z/OS DFHSM / DFDSS
- Db2 for z/OS V12
LOBs
- z/FS in V2R3
- IBM Java
- Cobol
- C
- IBM Content Manager
OnDemand
- IBM Encryption Facility
- IBM Sterling
Connect:Direct®
- z/OS HTTP Server
- OpenSSH
- IBM MQ for z/OS

**No Charge:
Integrated Accelerator
for zEDC hardware
Built-in processor chips.**



**z/OS software feature
required for exploitation
of:**

- z/OS SMF Logstream
- z/OS QSAM/BSAM
- z/OS DFHSM / DFDSS
- Db2 for z/OS V12
LOBs
- z/FS in V2R3

**No z/OS software feature
required for exploitation
of:**

- IBM Java
- Cobol
- C
- IBM Content Manager
OnDemand
- IBM Encryption Facility
- IBM Sterling
Connect:Direct®
- z/OS HTTP Server
- OpenSSH
- IBM MQ for z/OS

z15 Linux on Z Compression



Supported with

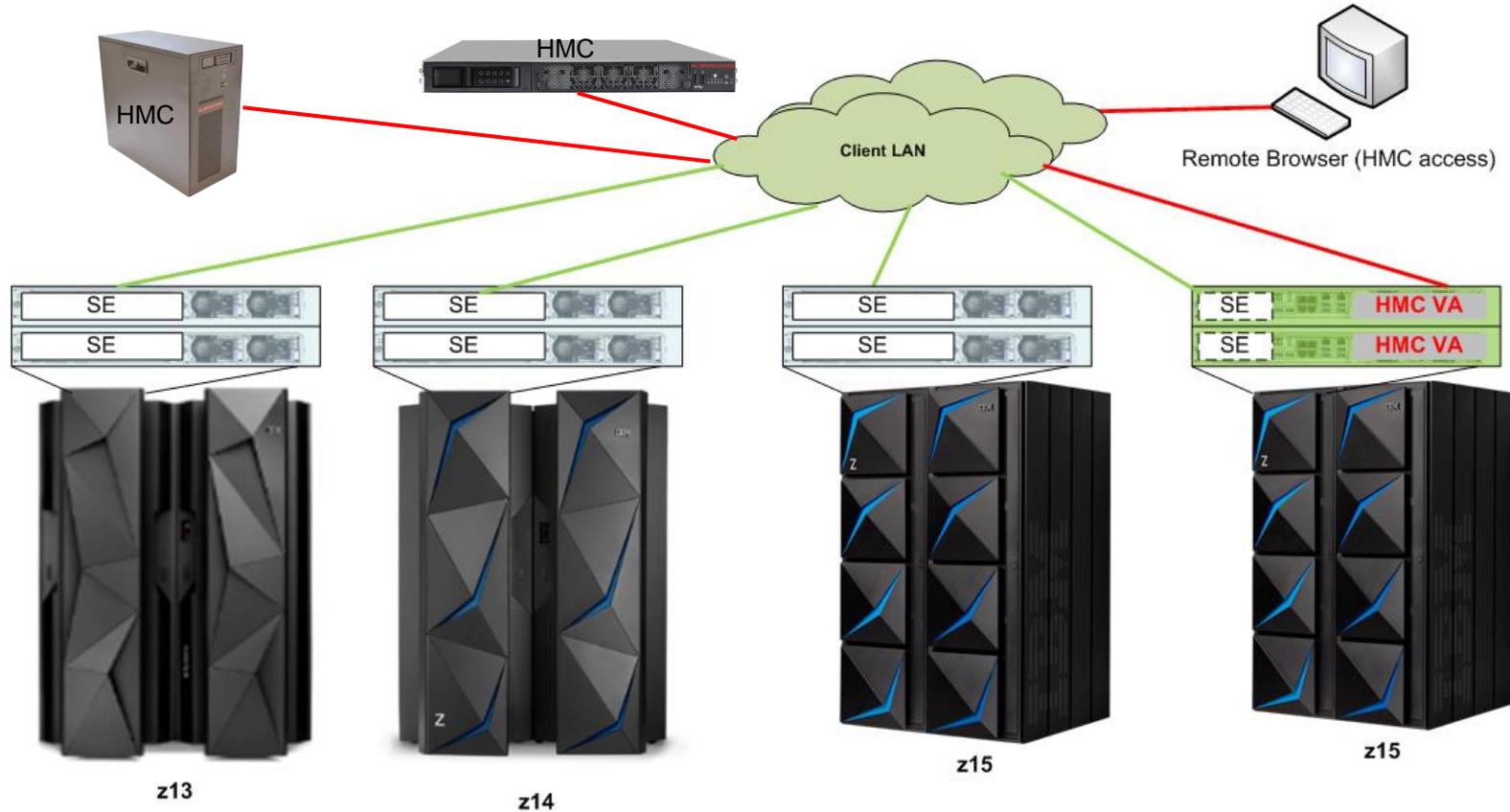
- Red Hat RHEL 8.1
- SUSE SLES 12 SP5
- Ubuntu 20.04

<https://linux.mainframe.blog/zlib-acceleration>

- On-Chip Compression provides value for existing and new compression users
- Less CPU consumption for compression
- Fully enabled in highly virtualized environments
 - All LPARs and VMs (z/VM & KVM) have 100% access
 - Avoids having to pick and choose which Linux guests may use accelerator
- Most beneficial for:
 - Java (e.g. IBM WebSphere Application Server)
 - Backup (e.g. for DBs)
 - Network traffic (e.g. Apache, NGINX)
 - IBM MQ

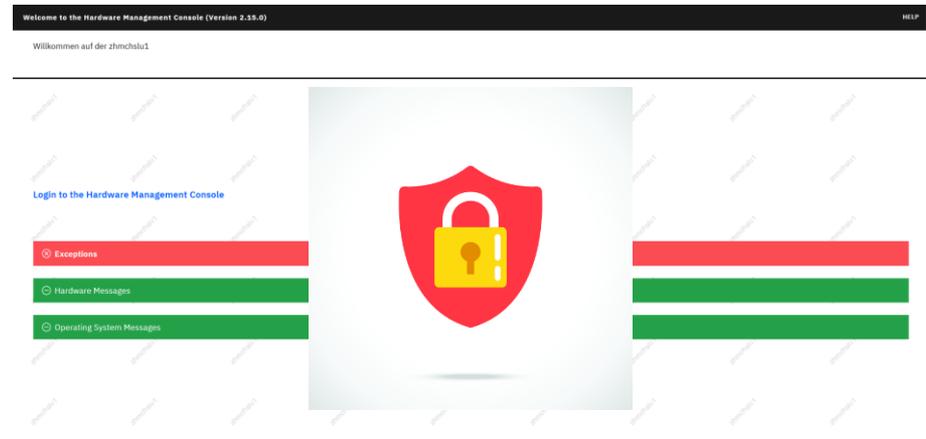
HMC / SE

IBM Z Hardware Management Appliance (HMA)



HMC default users

- Change default passwords (SYSPROG, ACSADMIN)
- Password for SERVICE -> change as well, but must be provided to the IBM technician
- Use personalized User IDs (just disable, NOT delete default users)
- Enable HMC Data Replication



HMC Multifactor Authentication – MFA

IBM Hardware Management Console Workplace (Version 2.15.0)

IBM Hardware Management Console

Home User Management

User Management

Multi-Factor Authentication

Configure users and templates for multi-factor authentication with HMC Multi-Factor Authentication (HMC MFA) or with IBM Multi-Factor Authentication for z/OS (IBM MFA).

IBM MFA HMC MFA

Users and templates

Configure HMC MFA for users and templates.

<input type="checkbox"/>	Name	Type	HMC MFA
<input type="checkbox"/>	ACADMIN	User	<input type="checkbox"/>
<input type="checkbox"/>	ADVANCED	User	<input type="checkbox"/>
<input type="checkbox"/>	hmcmauser	User	<input checked="" type="checkbox"/>
<input type="checkbox"/>	OPERATOR	User	<input type="checkbox"/>

Guidance

Multi-Factor Authentication is an authentication method in which an HMC user is granted access only after successfully presenting their user ID, password, and another authentication factor. The HMC provides two multi-factor authentication options.

HMC Multi-Factor Authentication (HMC MFA) provides Time-based One-Time Password (TOTP) authentication. After enabling HMC MFA users will be required to set up multi-factor authentication the next time they login.

IBM Multi-Factor Authentication for z/OS (IBM MFA) provides RSA SecurID authentication through IBM MFA servers. Define IBM MFA servers and then configure users and

Close Help

User Management Multi-Factor Authentication tab updated to support both

- HMC MFA Time-based One-time Password (TOTP)



IBM Security Verify



Google Authenticator

- IBM MFA for z/OS



Questions?

End of Section



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IBM*	IBM Z*	z/OS*	

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